



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Parameters	Ratings	Units
Peak Blocking Voltage	350	V_p
Load Current	130	mA_{rms} / mA_{DC}
On-Resistance (max)	30	Ω
Isolation Voltage, Input to Output	5000	V_{rms}

Features

- 5000V_{rms} Input/Output Isolation
- 350V_p Blocking Voltage
- Low Drive Power Requirements
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Small 4-Pin Package

Applications

- Telephony Switching
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

The CPC1333G is a single-pole, normally closed (1-Form-B) Solid State Relay with an enhanced input to output isolation barrier of 5000V_{rms}.

The relay output is constructed with efficient MOSFET switches that use IXYS Integrated Circuits Division's patented OptoMOS architecture. The input, a highly efficient infrared LED, controls the optically coupled output.

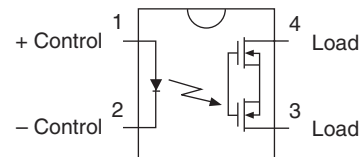
Approvals

- UL Recognized Component: File E76270
- EN/IEC 60950-1 Certified Component: TUV Certificate B 13 12 82667 003

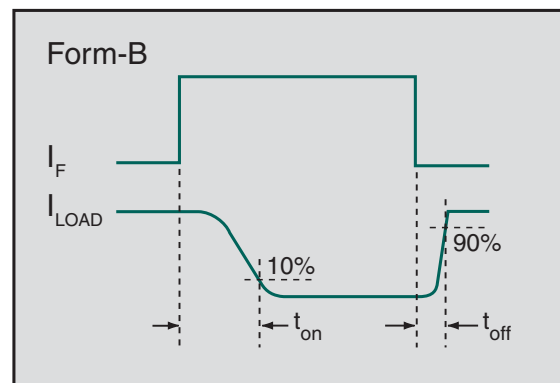
Ordering Information

Part Number	Description
CPC1333G	4-Pin DIP (100/Tube)
CPC1333GR	4-Pin Surface Mount (100/Tube)
CPC1333GRTR	4-Pin Surface Mount (1000/Reel)

Pin Configuration



Switching Characteristics of Normally Closed Devices



Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Peak Blocking Voltage	350	V _P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation ¹	100	mW
Total Package Dissipation ²	550	mW
Isolation Voltage, Input to Output	5000	V _{rms}
ESD Rating, Human Body Model	8	kV
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33mW / °C

² Derate linearly 3mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

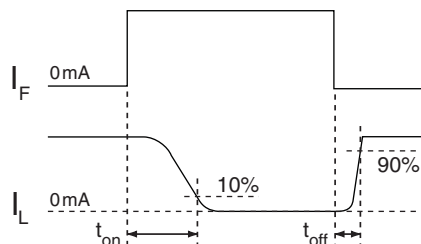
Electrical Characteristics @ 25°C

Parameters	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current						
Continuous	-	I _L	-	-	130	mA _{rms} / mA _{DC}
Peak	t=10ms	I _{LPK}	-	-	±350	mA _P
On-Resistance ¹	I _L =130mA	R _{ON}	-	25	30	Ω
Off-State Leakage Current	I _F =2mA, V _L =350V	I _{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On	I _F =5mA, V _L =10V	t _{on}	-	-	2	ms
Turn-Off		t _{off}	-	-	3	
Output Capacitance	I _F =2mA, V _L =50V, f=1MHz	C _{OUT}	-	6	-	pF
Input Characteristics						
Input Control Current to Activate ²	-	I _F	-	0.18	2	mA
Input Control Current to Deactivate	I _L =130mA	I _F	0.1	-	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.26	1.4	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Common Characteristics						
Capacitance, Input to Output	V _{IO} =0V, f=1MHz	C _{IO}	-	3	-	pF

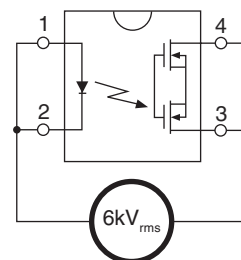
¹ Measurement taken within one second of on-time.

² For high temperature operation (> 60°C), IXYS Integrated Circuits Division recommends a minimum LED drive current of 5mA.

Timing Diagram



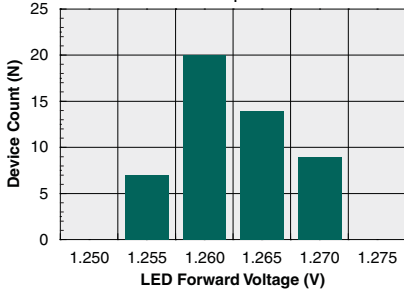
CPC1333G Isolation Test Circuit



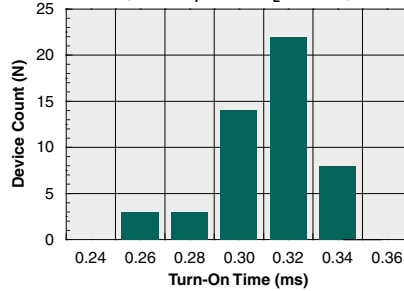
Test Conditions:
 Voltage Ramp: 2V/μs
 Test Time: 2 Seconds
 I_{LEAK} Threshold: 50μA
 Test Voltage: 6kV_{rms}

PERFORMANCE DATA @25°C (Unless Otherwise Noted)*

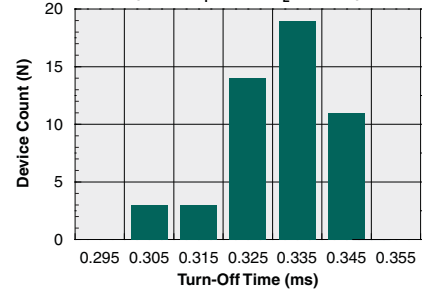
Typical LED Forward Voltage Drop
(N=50, I_F=5mA)



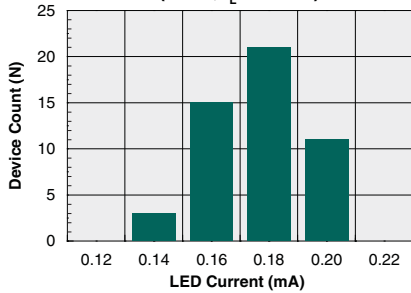
Typical Turn-On Time
(N=50, I_F=5mA, I_L=60mA)



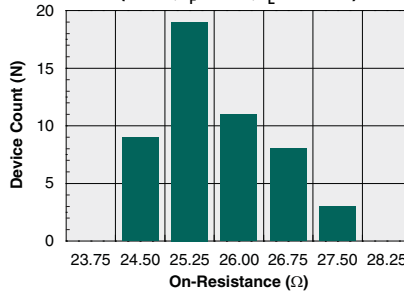
Typical Turn-Off Time
(N=50, I_F=5mA, I_L=60mA)



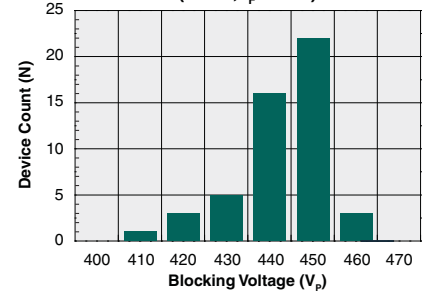
Typical I_F for Switch Operation
(N=50, I_L=130mA)



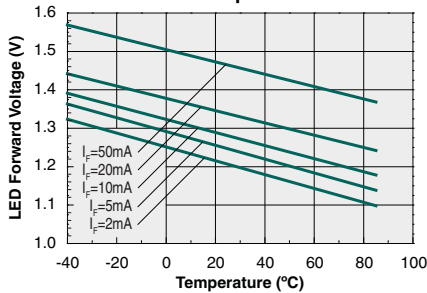
Typical On-Resistance Distribution
(N=50, I_F=0mA, I_L=130mA)



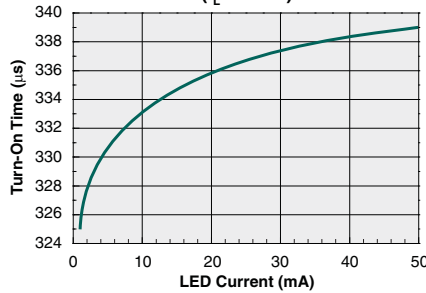
Typical Blocking Voltage Distribution
(N=50, I_F=2mA)



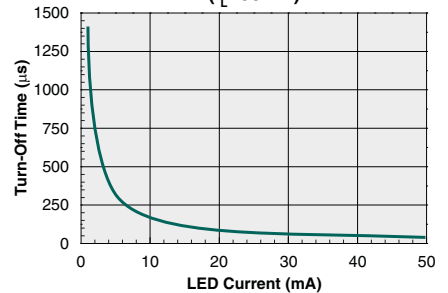
Typical LED Forward Voltage Drop
vs. Temperature



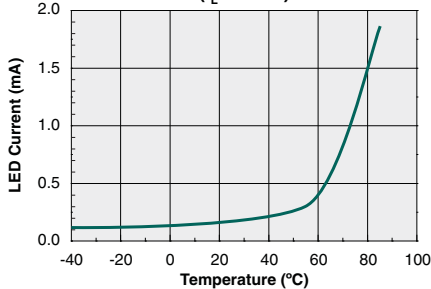
Typical Turn-On Time
vs. LED Forward Current
(I_L=60mA)



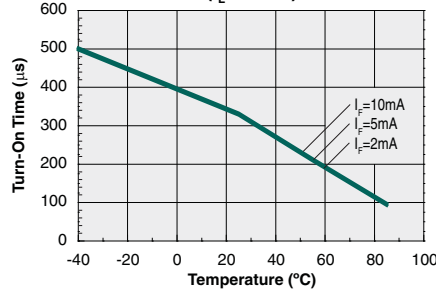
Typical Turn-Off Time
vs. LED Forward Current
(I_L=60mA)



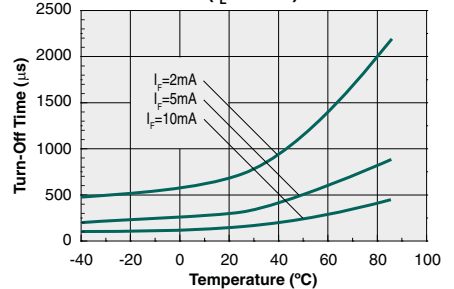
Typical I_F for Switch Operation
vs. Temperature
(I_L=60mA)



Typical Turn-On Time
vs. Temperature
(I_L=60mA)

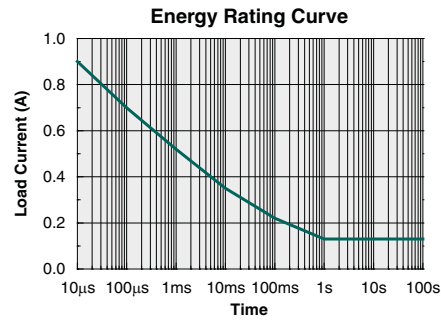
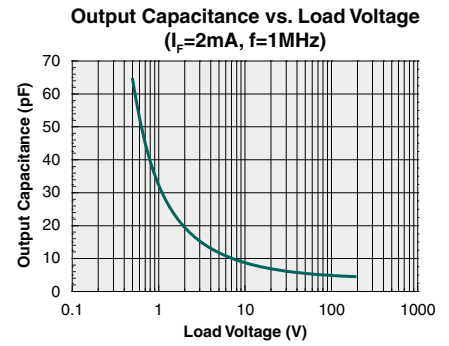
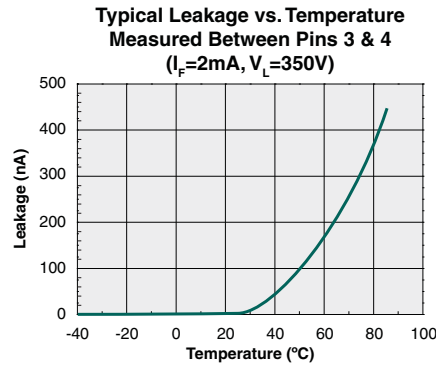
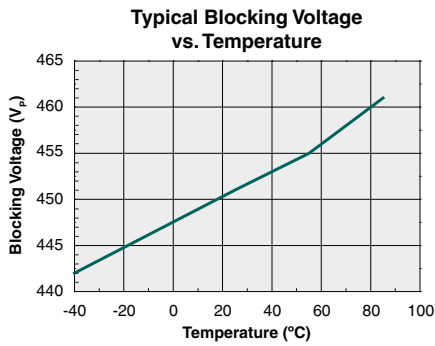
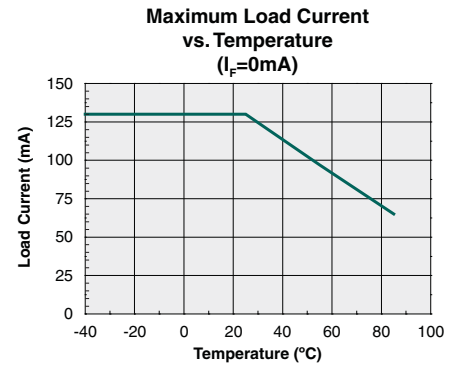
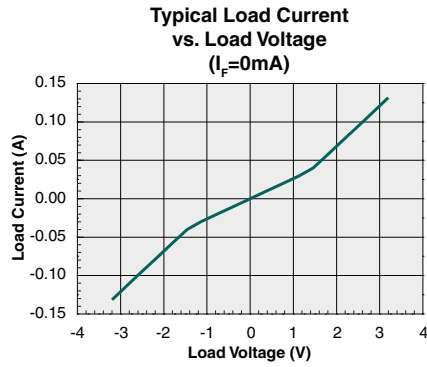
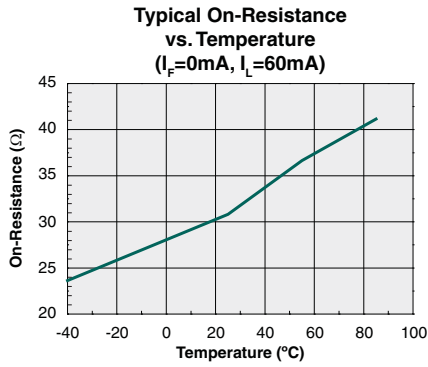


Typical Turn-Off Time
vs. Temperature
(I_L=60mA)



* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA @25°C (Unless Otherwise Noted)*



* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC1333G	MSL 1
CPC1333GR	MSL 3

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

Provided in the table below is the Classification Temperature (T_C) of this product and the maximum dwell time the body temperature of this device may be above ($T_C - 5$)°C. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. Additionally, for the CPC1333GR, the solder reflow profile given in Technical Brief TB-200 "**Pb-Free Solder Reflow Profile for Select Devices**" must be followed. For the through-hole device, CPC1333G, and any other processes, the guidelines of **J-STD-020** must be observed.

Device	Maximum Body Temperature (T_C)	Time
CPC1333GR	250°C	15 seconds

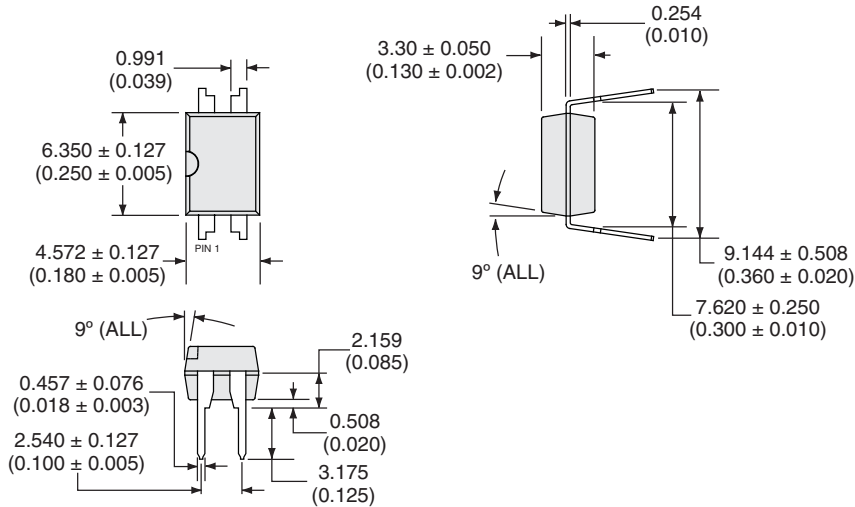
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow-up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device, and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.

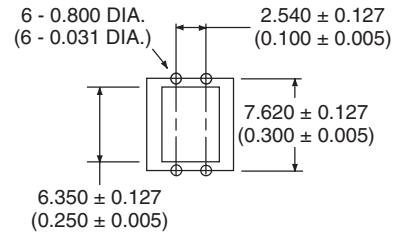


Mechanical Dimensions

CPC1333G

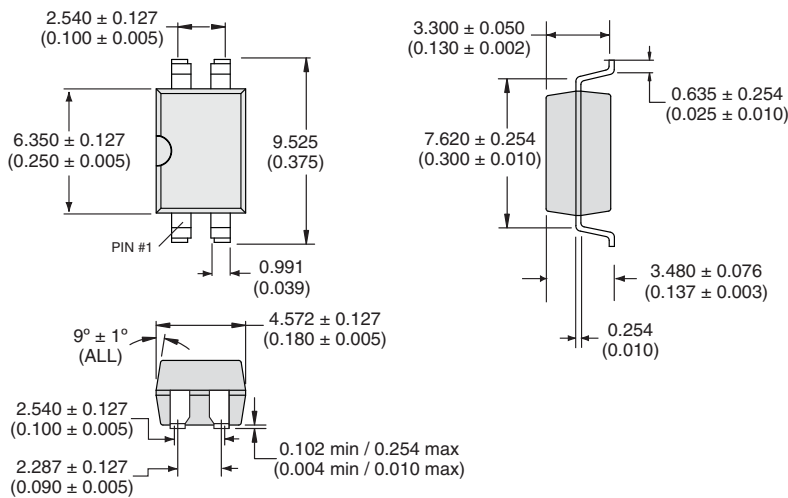


PC Board Pattern (Top View)

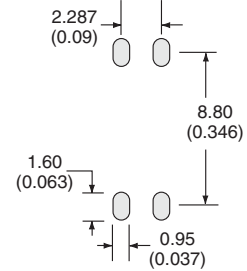


Dimensions
mm
(inches)

CPC1333GR

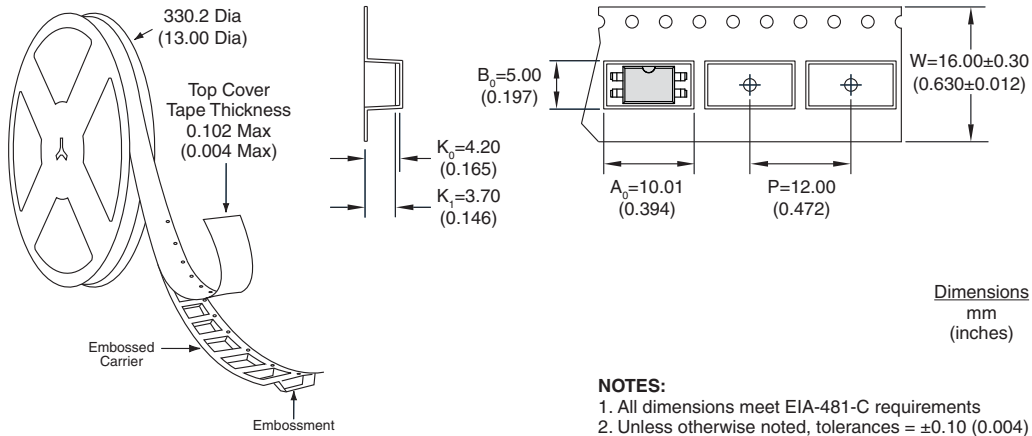


PCB Land Pattern



Dimensions
mm
(inches)

CPC1333GRTR Tape & Reel



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